IPC ASSOCIATION CON ELECTRONICS IND	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier In	formation	,												
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-13				
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
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Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	W	eight*	UOM	Unit Type
	FDMF3037 Smart Power Stag		Smart Power Stage	Module		2024-05-13 MY5		1 Y5	73	.67428	mg	Each		
	ring Proccess Informa													
2 7		, and the second		STD-020 MSL	Rating	Peak Process Body Tempera						er of Reflow Cyc	eles	
Ma	tte Tin (Sn) - annealed		CU Alloy	1			260		C	30	seconds	3		
omments														
	num time at peak temperat	8												
or more info	rmation regarding materia	l composition	please refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the content of the content with the supplier of the content	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.34295	mg	Supplier	Zinc (Zn)	7440-66-6		0.0076	mg
			Supplier	Iron (Fe)	7439-89-6		0.1522	mg
			Supplier	Copper (Cu)	7440-50-8		6.178	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0051	mg
Die	0.317142	mg	Supplier	Silicon (Si)	7440-21-3		0.3171	mg
Die Attach Solder	2.17762	mg	Supplier	Silver (Ag)	7440-22-4		0.0544	mg
			A	Lead (Pb)	7439-92-1	7a	2.0143	mg
			Supplier	Tin (Sn)	7440-31-5		0.1089	mg
Epoxy	0.1291	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0103	mg
			Supplier	Proprietary	Proprietary Data		0.0116	mg
			Supplier	Bismaleimide	13676-54-5		0.0349	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0013	mg
			Supplier	PTFE	9002-84-0		0.071	mg
Lead Frame	31.0723	mg	Supplier	Silver (Ag)	7440-22-4		1.5538	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0373	mg
			Supplier	Iron (Fe)	7439-89-6		0.7458	mg
			Supplier	Copper (Cu)	7440-50-8		28.7106	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	31.2746	mg		Proprietary	proprietary data		2.502	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1564	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.6163	mg
Plating	2.10085	mg	Supplier	Tin (Sn)	7440-31-5		2.1009	mg
Wire Bond - Cu	0.259717	mg	Supplier	Palladium (Pd)	7440-05-3		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.2548	mg